

Application deadline: May 15, 2009

Applications will not be reviewed until complete. Please include the following information:

- Completed application form
- \$50 non-refundable application fee made payable to "JHU"
- Official high school transcripts, including grades through December, 2008
- Copy (not official) of most recent standardized test scores (PSAT, SAT, ACT, PLAN, TOEFL)
- Recommendation from a math or science teacher
- If applicable, completed Financial Aid form with supporting documents
- If international student, financial statement in support of the program

Program Site –pick one. All sites commuter except where noted.

Please refer to <http://engineering-innovation.jhu.edu> for site addresses and specific dates and times.

California:

- Channel Islands, Camarillo, California State University Pasadena, Pasadena City College
 Fullerton, California State University Santa Barbara, Univ. of California (**MESA students only**)
 Los Angeles, California State University Stockton, University of the Pacific (**MESA students only**)
 Thousand Oaks, California Lutheran University

Maryland:

- Baltimore, Johns Hopkins University commuter residential (additional **\$1900**, Baltimore only)
 Bel Air, Harford Community College Rockville, Johns Hopkins University
 Elkridge, Johns Hopkins University Westminster – Carroll Community College
 Frederick, Tuscarora High School

New Mexico

- Albuquerque, Albuquerque Academy

Pennsylvania:

- Harrisburg, SciTech High School

Applicant Information – information must be complete – please write clearly

Name: _____

Address: _____

City: _____ State: _____ Zip: _____

If International Student: Student's Citizenship _____ Country of birth _____

Foreign home address if different from address in applicant information:

Phone: _____ Email: _____

Gender: Male Female Birth date: _____ Current Grade: _____

Social Security Number: _____

Is anyone in your family a JHU alum or currently attending JHU? _____ Relationship _____

Who will be responsible for payment of tuition?

Parent/Guardian Applying for JHU Financial Aid MESA Upward Bound

Other Sponsoring Organization (please identify) _____

Contact person _____ Phone: _____

Ethnicity: (please check all that apply)

- African American Caucasian Mexican American Puerto Rican
 Asian/Pacific Islander Hispanic Native American Other _____

How did you hear about this program?

- Post card Teacher Internet Friend/ Relative
 In class presentation Guidance office Poster/flyer Other _____

T-shirt Size (men's sizing) : Small Medium Large Extra Large XXL

School Information – information must be complete – please write clearly

High School Name: _____ School Phone: _____

Address: _____

City: _____ State: _____ Zip: _____

Web Site: _____ Principal: _____

Guidance Counselor: _____ Math or Science Teacher: _____

Type of School: Public Parochial Private/Independent Home School

Parent/Guardian/Student Agreement–required by Johns Hopkins University

I approve of this application and will permit _____ to attend Engineering Innovation, Summer 2009, offered through The Johns Hopkins University. If my student is accepted and enrolled, I agree to pay all tuition costs unless tuition covered by JHU financial aid or by a sponsoring organization. I recognize that refunds can only be made according to the published refund schedule. Also, I understand the necessity for my student's conformance to the academic and social policies of this program and of The Johns Hopkins University, and that failure to abide by these regulations may result in my student's dismissal without tuition refund.

Signature of Parent/ Guardian _____ Date: _____

I understand that a grade of an "A" or "B" is required to obtain JHU transferable credits. Those students passing the class with lower than a "B" will be issued a Certificate of Completion. Daily attendance and completion of the final exam is required to receive college credit. All absences must be approved in advance by the instructor. Medical absences will be given special consideration.

If admitted to Engineering Innovation, I agree to abide by the academic and social policies of the program and of The Johns Hopkins University (<http://engineering.jhu.edu/include/content/pdf/acadaff/2007-UG-Handbook.pdf> pages 41, 48, 56-62).

Signature of Student _____ Date: _____

Signature of Parent/ Guardian _____ Date: _____

Print Name: _____

Street Address (if different than student) _____

City: _____ State: _____ Zip: _____

Home Phone (if different from student): _____

Work Phone or Cell Phone: _____

Email (write clearly) _____

I understand that failure to abide by these regulations may result in dismissal and that any student dismissed from the program does not receive a refund and will receive a "W" (withdrawn) on their transcript.

Please return all application materials to: Engineering Innovation / Johns Hopkins University / 3400 N. Charles Street / Maryland Hall 221 / Baltimore, MD 21218

<http://engineering-innovation.jhu.edu>